

Hirose Korea TCP/FFC Connector

TF09-Series

목 차

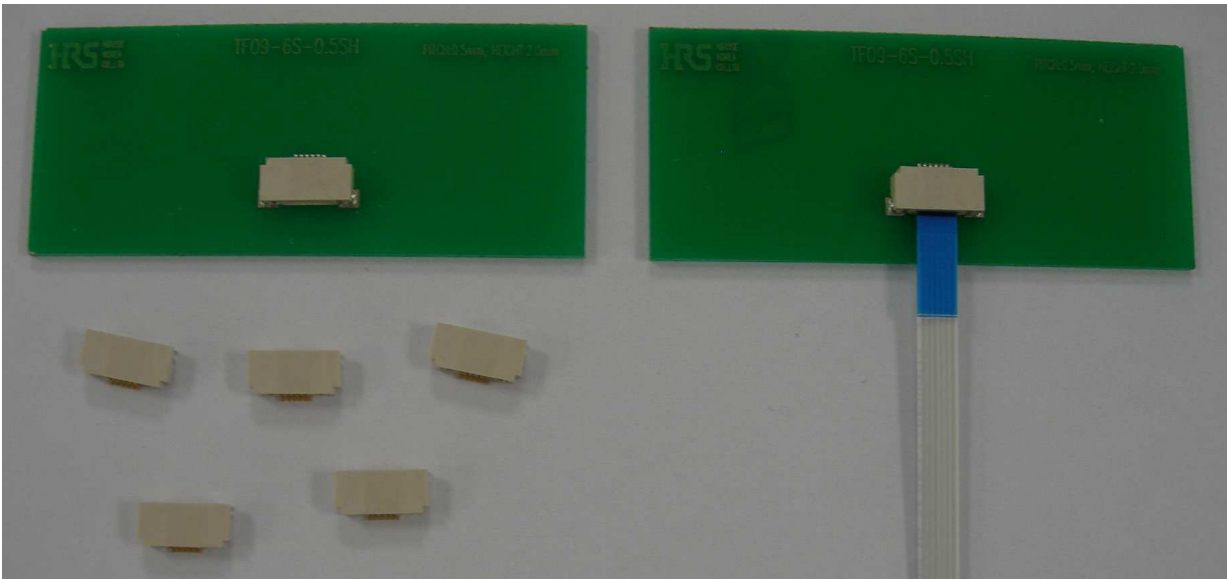
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No.	제 품 명	Pin 수	사양	관련 page
1	TF09-6S-0.5SH	16	0.5 Pitch ,2mm 높이,FFC 사양	2~3

- 4.Reflow profile (Lead-free)-----page 6

TF09 - ** S-0.5SH

0.5mmPitch, 2.0mm Height, Single contact, Non ZIP type FFC/FPC Connectors



■ Feature

1. PITCH 0.5mm, HEIGHT 2mm FPC 커넥터
2. Non-ZIP Type
3. On-Board Type
4. FPC 삽입 및 발거 작업성 용이
5. FPC의 충분한 삽입길이 확보로 접촉신뢰성 확보
6. RoHS 및 Halogen Free 대응 원재료 사용

■ Part Number의 구성

TF09 - ** S - 0.5 SH
 ① ② ③ ④ ⑤

①	Serial Name	고유ID
②	Contact 수	Pin : 6
③	Contact 분류	S : socket
④	Contact Pitch	0.5mm
⑤	Solder 방식	SH : SMT horizontal mounting type

■ 제품 규격

Rating	Current 0.5A	Operating temperature range	Storage temperature range
	Voltage 50V	- 55 °C ~ + 85 °C	- 10 °C ~ + 50 °C

Item	Specification	Conditions
1. Insulation Resistance	500MΩ Min	Measured at 100V DC
2. Withstand voltage	Neither shot or insulation breakdown	150V AC for 1 minute
3. Contact Resistance	100mΩ Max	Measured at 1mA(or 1,000Hz)
4. FFC Retention Force	Ver:1.2kgf MIN/Hor:1.8kgf MIN	Measure at 0.3±0.03mm FFC
5. Mechanical operation	Contact Resistance : 100mΩ Max	20 Time insertions and extractions.
6. Moisture Resistance	Temperature : 40±2°C	Contact Resistance : 100mΩ Max Insulation Resistance : 500MΩ Min
	Relative Humidity : 90~95%	
	Duration : 96Hr	
7. Resistance to Soldering heat	Reflow : 150~200°C 60~180Sec , 217°C 60~150sec, Peak 255 ± 5°C , Peak 5°C	No deformation of components affecting performance.

■ 부품별 적용 원재료

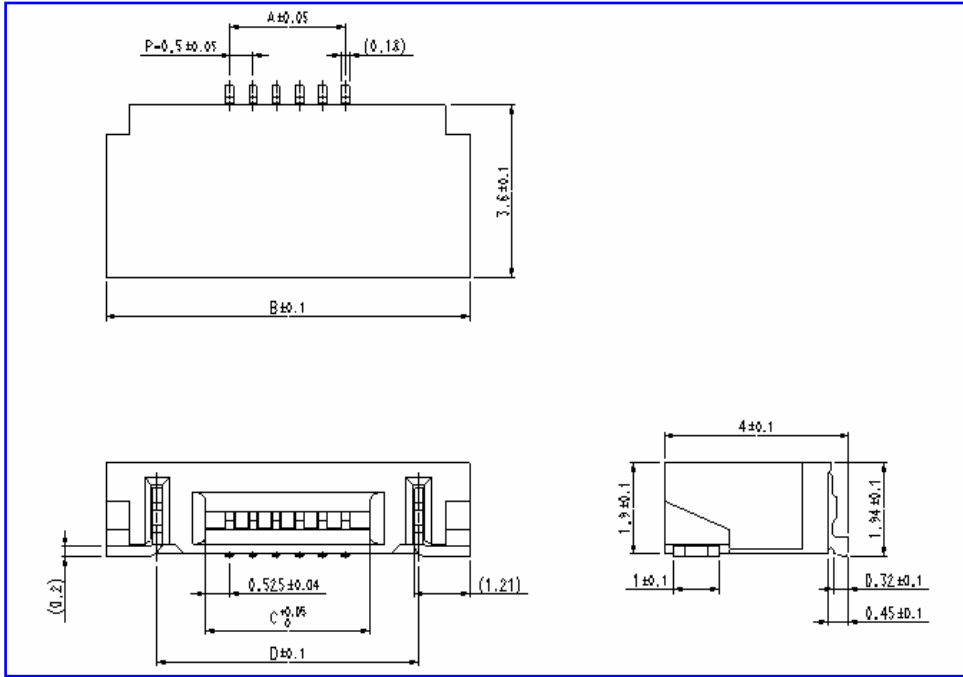
Part	Material	Finish	Remarks
CASE	LCP	NATURAL	UL94V-0
SIGNAL CONTACT	Phosphor Bronze	Gold plating over Ni	Ni Barrier
METAL FITTING	Phosphor Bronze	Sn over Ni plating	-

※ Reflow 최대 온도 250°C를 만족시킴으로 Lead-free Soldering의 요구조건에 적합한 제품임.

※ RoHS지침 및 유해 물질 관리 기준에 적합한 제품임.

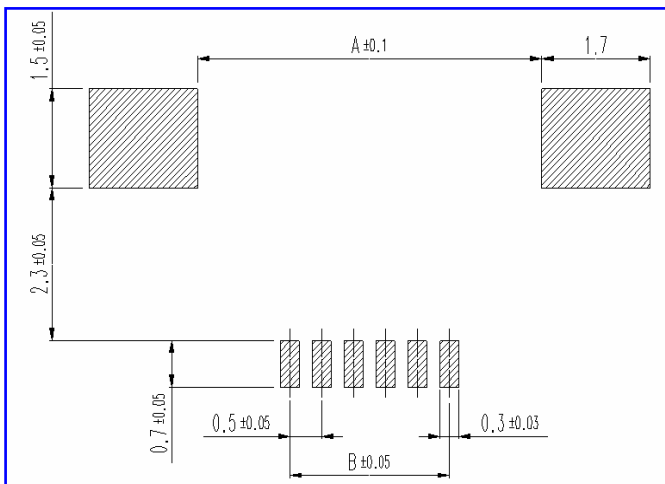
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TF09 - ** S - 0.5SH



	6S
A	2.5
B	7.88
C	3.55
D	5.66

PCB LAYOUT



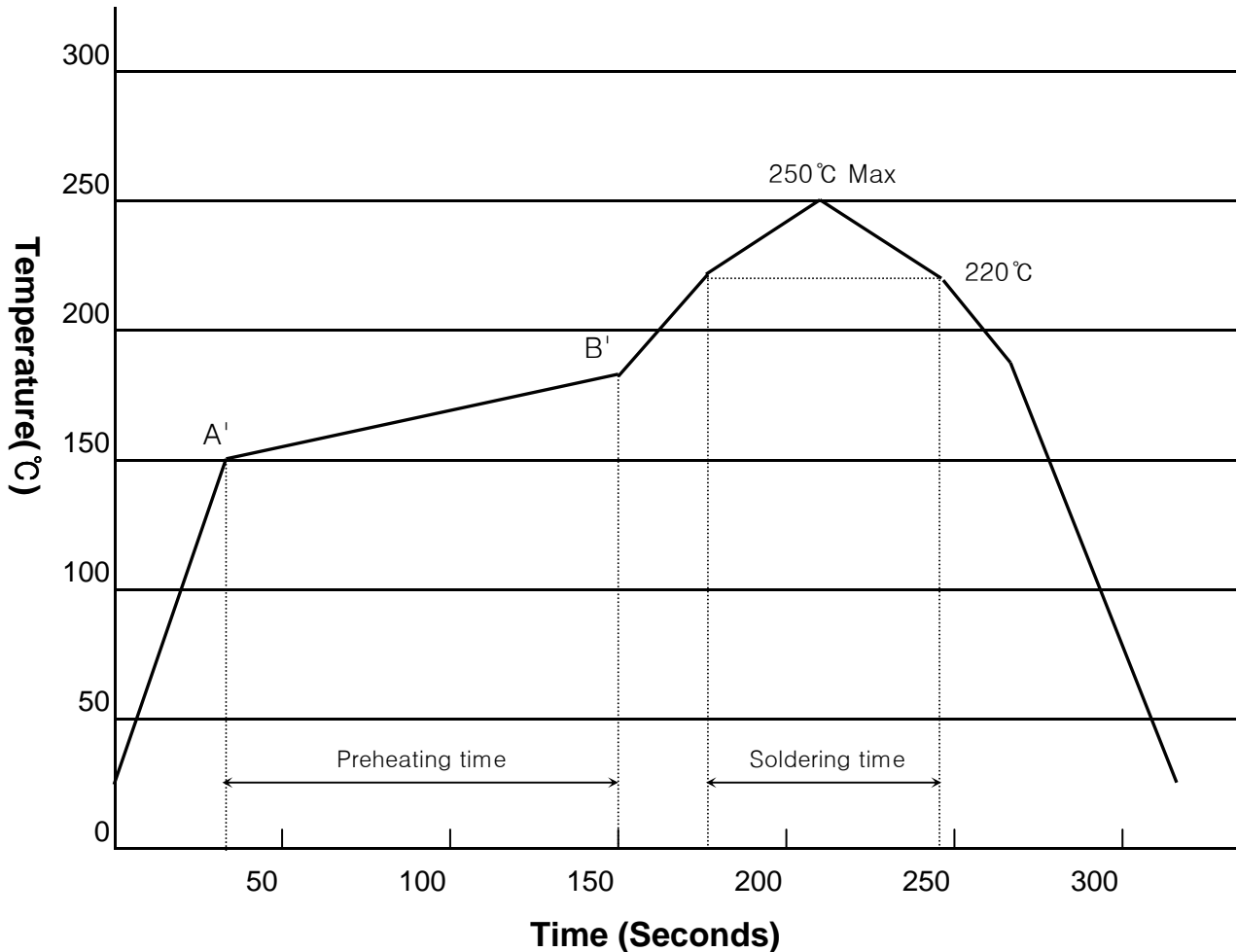
	6
A	5.2
B	2.5

■ Packaging Specification

- ◆ 포장 방법 : Embossed Carrier tape(Anti-static)
- ◆ 포장 수량 : 3,000pcs/Reel

■ Reflow Profile

Using Lead-free Solder Paste



Recommended Application Conditions

Reflow System: IR reflow

Solder: Cream type Sn / 3 Ag / 0.5 Cu

Flux content 11%wt

Metal mask thickness: 0.15mm

Preheating time: 150°C ~ 190°C, 90±30seconds

A'=150°C ~ 170°C, B'=170°C ~ 190°C

Soldering time: 260°C Max

220°C Min, 30~60 seconds